

ABSTRACT

The present invention is a circuit connecting material used for the mutual connection of a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, and a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, with the edge parts and of the insulating layers being formed with a greater thickness than the electrodes on the basis of the main surfaces, wherein this circuit connecting material contains a bonding agent composition and conductive particles that have a mean particle size of 1 μm or greater but less than 10 μm and a hardness of 1.961 to 6.865 GPa, and this circuit connecting material exhibits a storage elastic modulus of 0.5 to 3 GPa at 40°C and a mean coefficient of thermal expansion of 30 to 200 ppm/ $^{\circ}\text{C}$ at from 25°C to 100°C when subjected to the curing treatment.